

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190829000.1 Datasheet for TPS63050, TPS63051 Change Notification

Date:September 13, 2019To:Newark/Farnell PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN ww admin team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services

Data Sheet Change Notification Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

TPS63050RMWT TPS63051RMWT TPS63051YFFT TPS63050YFFT

CUSTOMER PART NUMBER

null null null null

Technical details of this Product Change follow on the next page(s).

PCN Number: 201908290			000.1			PCN Date:		Sept. 13, 2019			
Title: Datasheet for TPS63050, TPS63051											
Customer Contact: PCN Manager							Dept:		Quality Services		
Prop	posed 1 st Ship Da	ite:	13, 2019								
Cha	nge Type:			,							
	Assembly Site				Design				Wafer	⁻ Bump Site	
	Assembly Process			X Data Sheet				Wafer Bump Material			
	Assembly Materials			Part number change				Wafer	- Bump Process		
Mechanical Specification				Test Site				Wafer	⁻ Fab Site		
Packing/Shipping/Labeling				Test Process				Wafer Fab Materials			
								Wafer	- Fab Process		
Notification Details											
Description of Change:											
Texas Instruments Incorporated is announcing a change. The product datasheet(s) is being updated as summarized below.											
	INSTRUMENTS									TPS63050, TPS63051	
_							5	SLVSAN	ISD -JULY	2013-REVISED AUGUST 2019	
Changes from Revision C (July 2015) to Revision D Page											
Added Webench links to the data sheet											
	Changed the Pin Configurations										
 Added Note: Conditions: T_J = -40°C to 85°C To the quiescent current and shutdown current in the <i>Electrical</i> Characteristics											
	datasheet number	will b	e chang	ging						_	
Device Family				Change Fro	m:				ige To:		
TPS63050, TPS63051					SLVSAM8C				SLVSAM8D		
http://www.ti.com/product/TPS63050											
Rea	son for Change:										
To accurately reflect device characteristics.											
Anti	icipated impact o	on Fit,	Form,	Fu	nction, Qua	lity o	r Reliat	oility	(pos i	itive / negative):	
Electrical specification performance changes as indicated above.											
Changes to product identification resulting from this PCN:											
None	e.										
Product Affected:											
TPS	63050RMWR TPS6305			ORMWT TPS6			3050YFFR			TPS63050YFFT	
TPS	63051RMWR	TP	S63051	IRM	и т	TPS63	051YFFF	2		TPS63051YFFT	
For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.											

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com

Asia Pacific	PCNAsiaContact@list.ti.com				
Japan	PCNJapanContact@list.ti.com				

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